

Preferential Outward Diffusion of Ni in CuNi Alloy Proliferates Active Sites by An Order of Magnitude for OER and MOR

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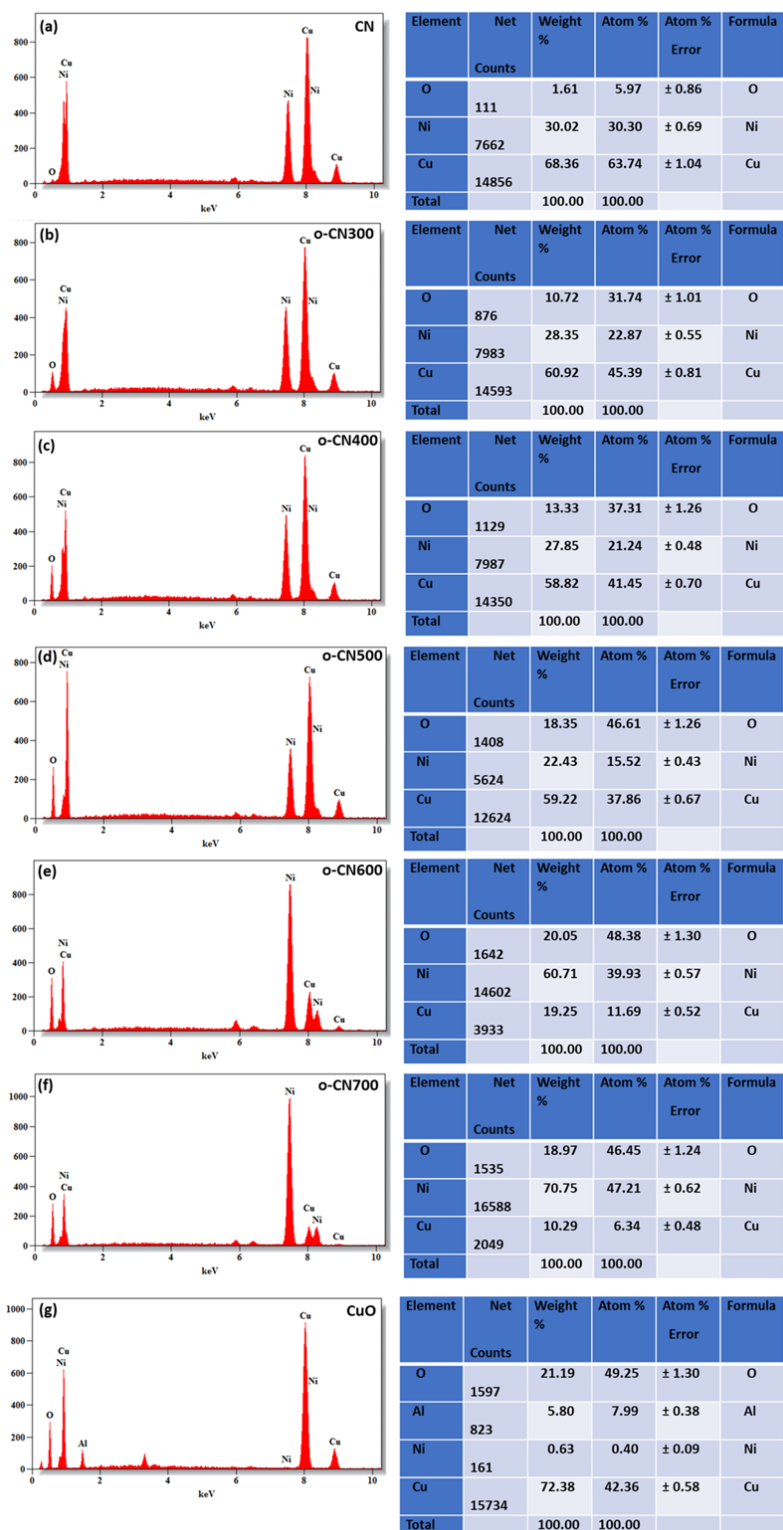


Figure S1: EDX spectra and corresponding elemental mapping of CN electrodes annealed at different temperatures: (a) pristine CN, (b) o-CN300, (c) o-CN400, (d) o-CN500, o-CN600, (e) o-CN700, and (g) peeled-off CuO. The maps show the distribution of Cu, Ni, and O, illustrating progressive surface oxidation with increasing annealing temperature.

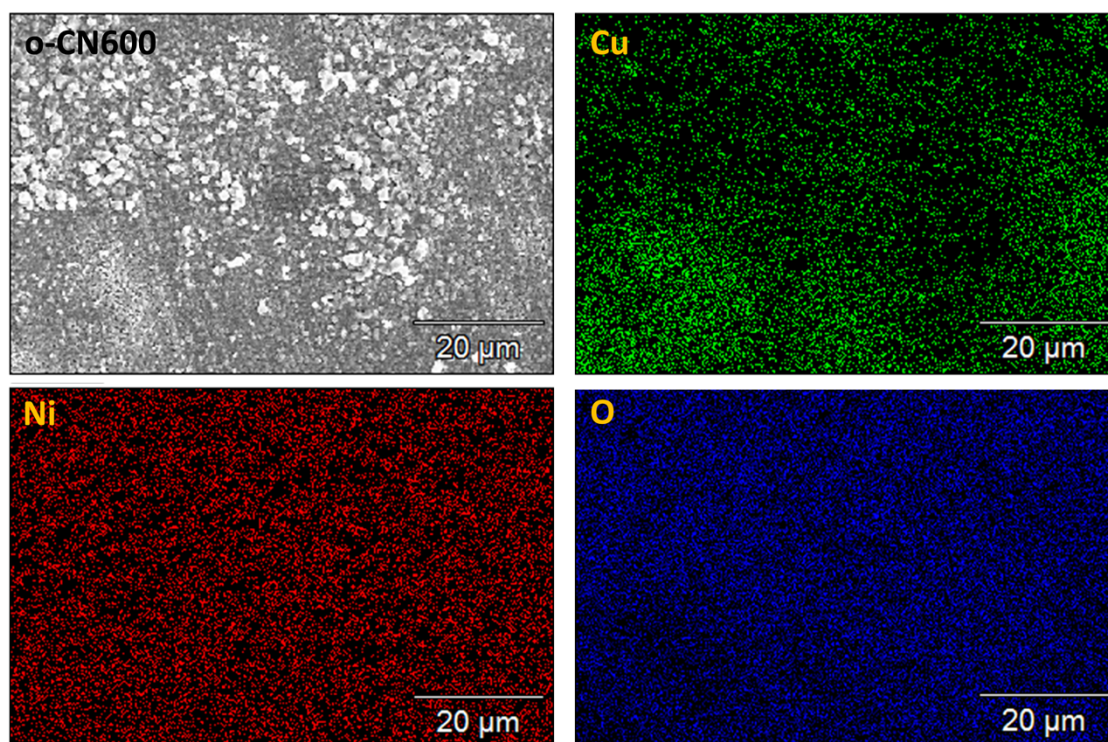


Figure S2: Elemental mapping of the CN electrode annealed at 600 °C (o-CN600), showing the distribution of Cu, Ni, and O.

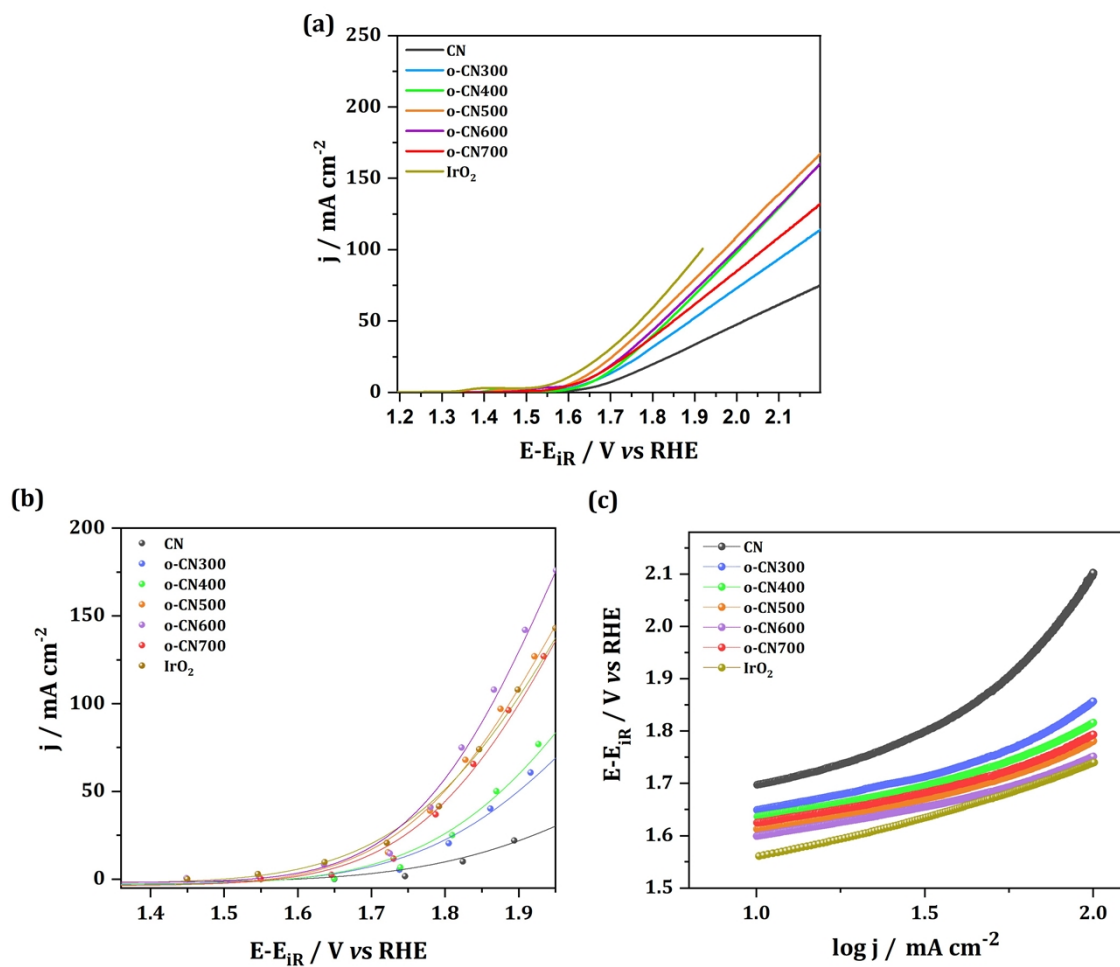
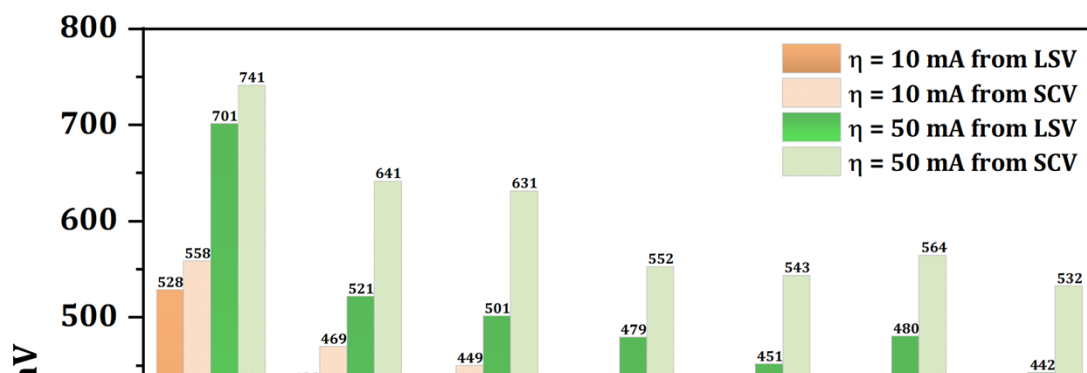


Figure S3: OER LSV curves of CN, o-CNX, and IrO₂/Ni without iR_u correction (a), SCV curves of CN and o-CNX (b), and corresponding Tafel plots derived from the LSV curves of CN and o-CNX (c).



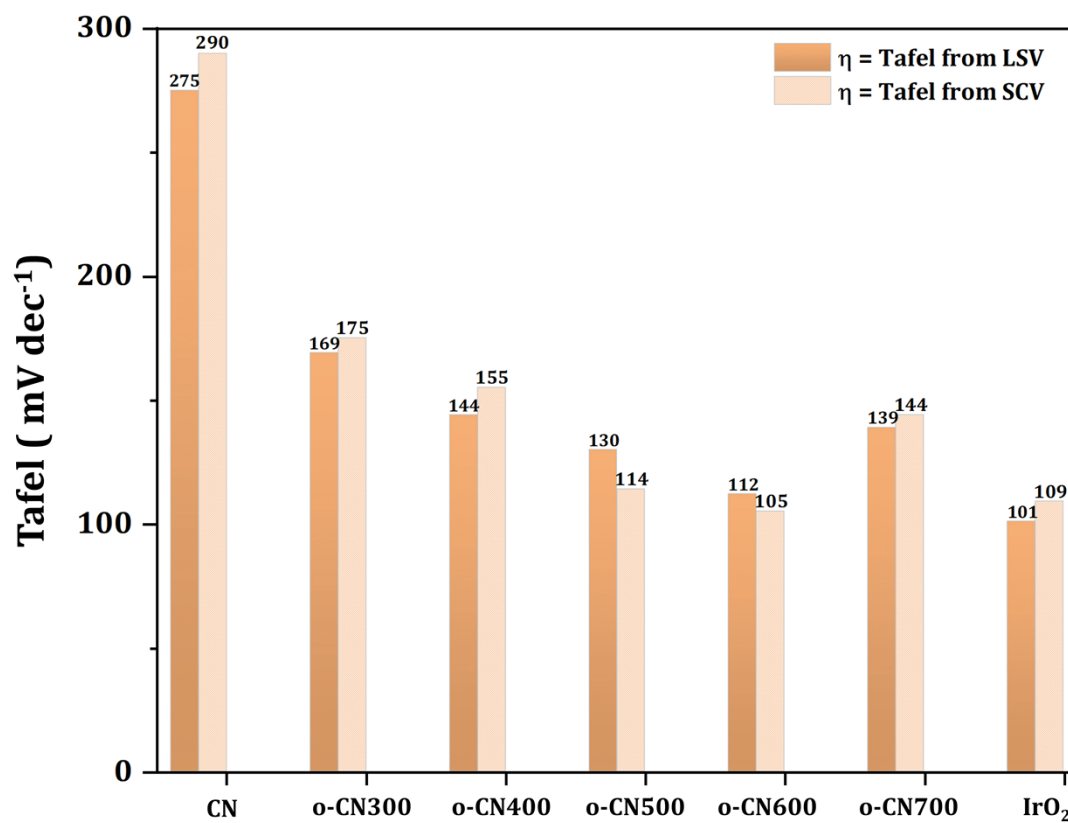


Figure S4: Overpotential comparison at 10 and 50 mA obtained from both LSV and SCV analyses.

Figure S5: Tafel comparison obtained from both LSV and SCV analyses.

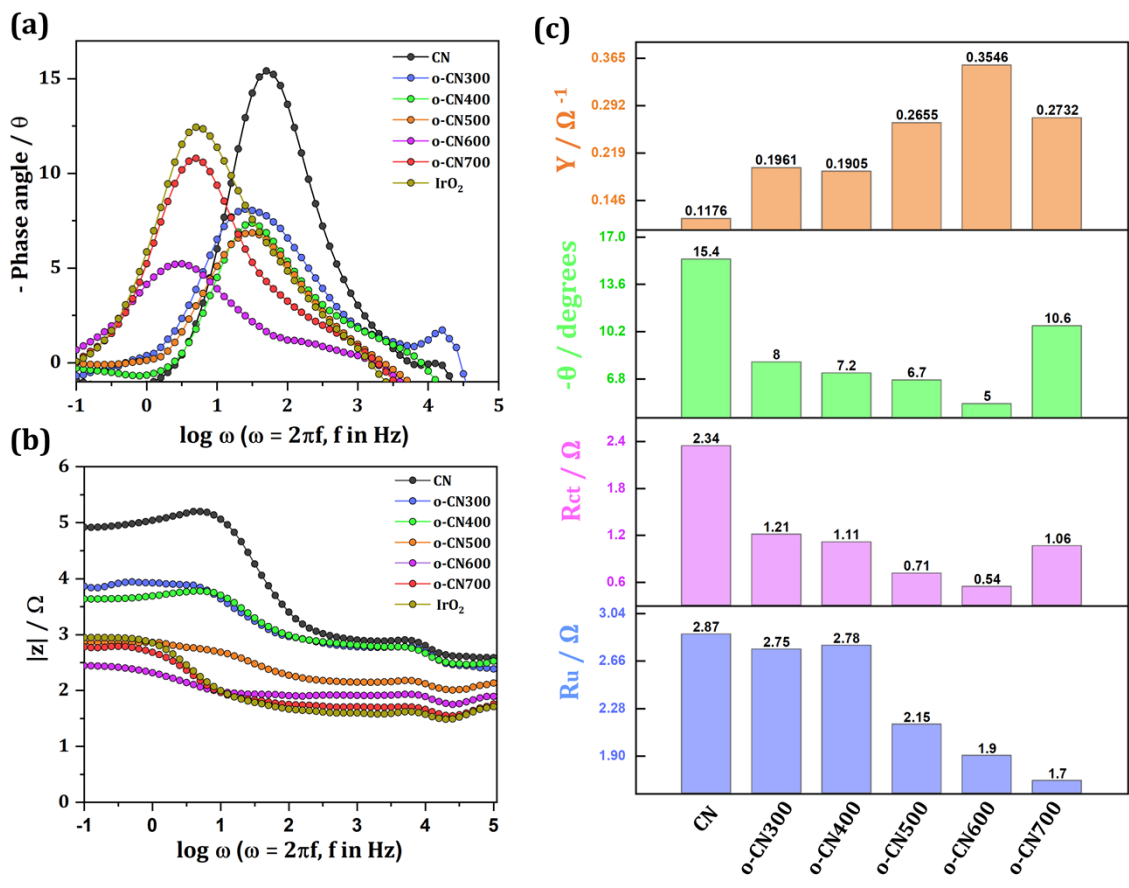


Figure S6: Bode phase-angle spectra (a); Bode magnitude plot showing the absolute impedance (b); and the corresponding EIS-derived parameters (c) for the CN and o-CNX during the OER process.

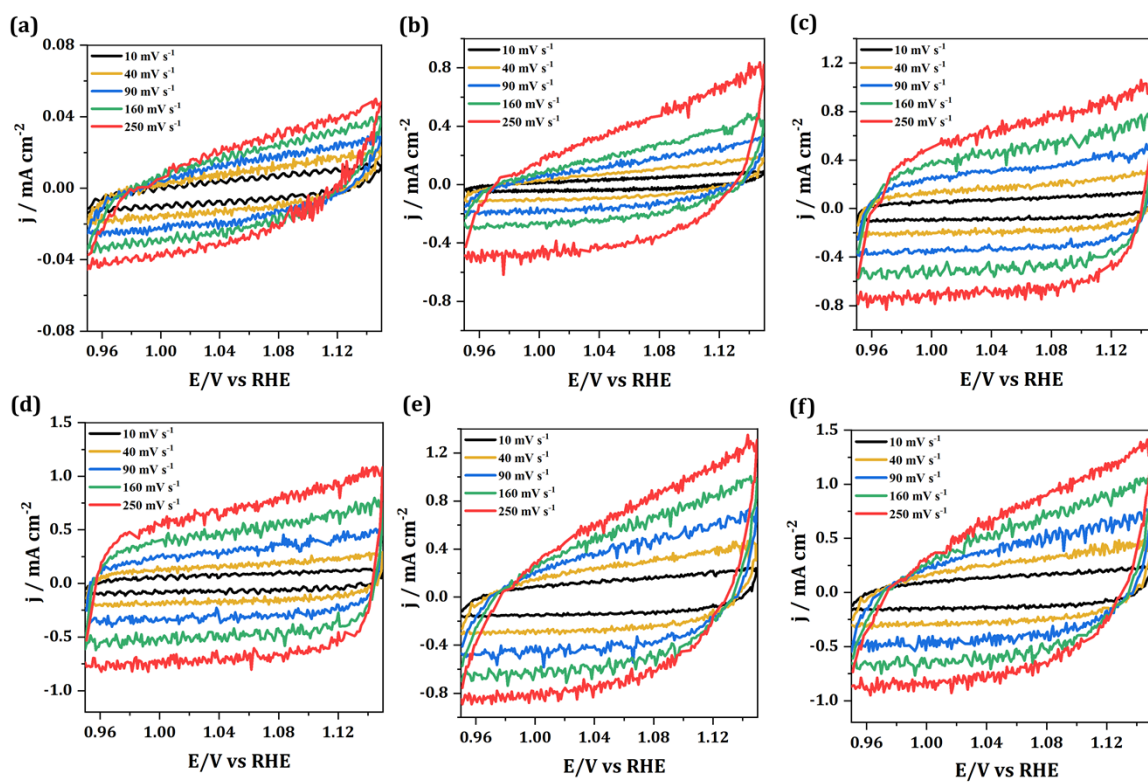


Figure S7: Panels (a–f) illustrate the electrochemical behavior within the non-Faradaic region of o-CNX.

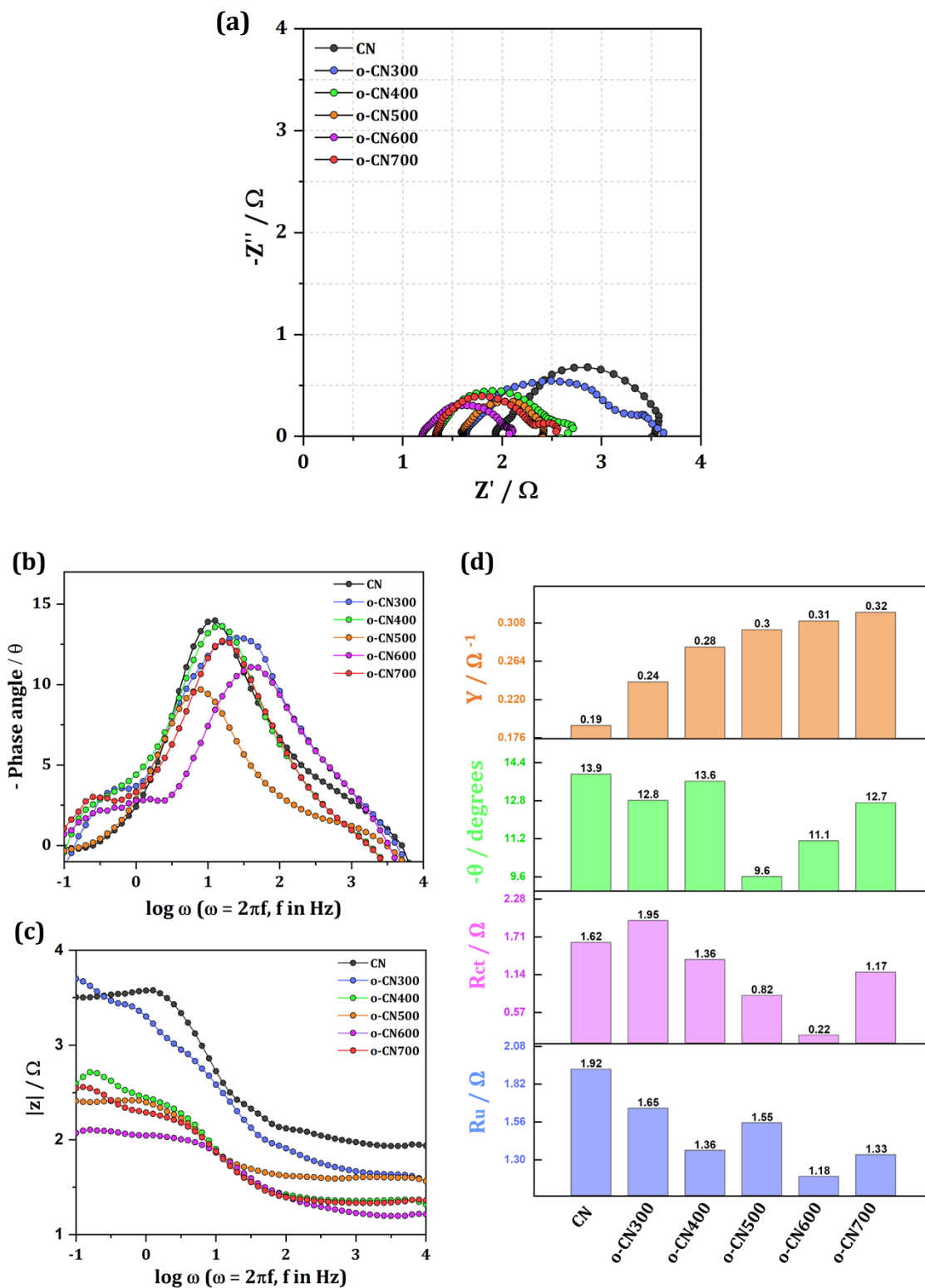


Figure S8: Nyquist plots for the CN and o-CNX series (a); Bode phase-angle plot (b); Bode magnitude plot showing the absolute impedance (c); and the corresponding EIS-derived parameters (d) for the CN and o-CNX during the MOR process.

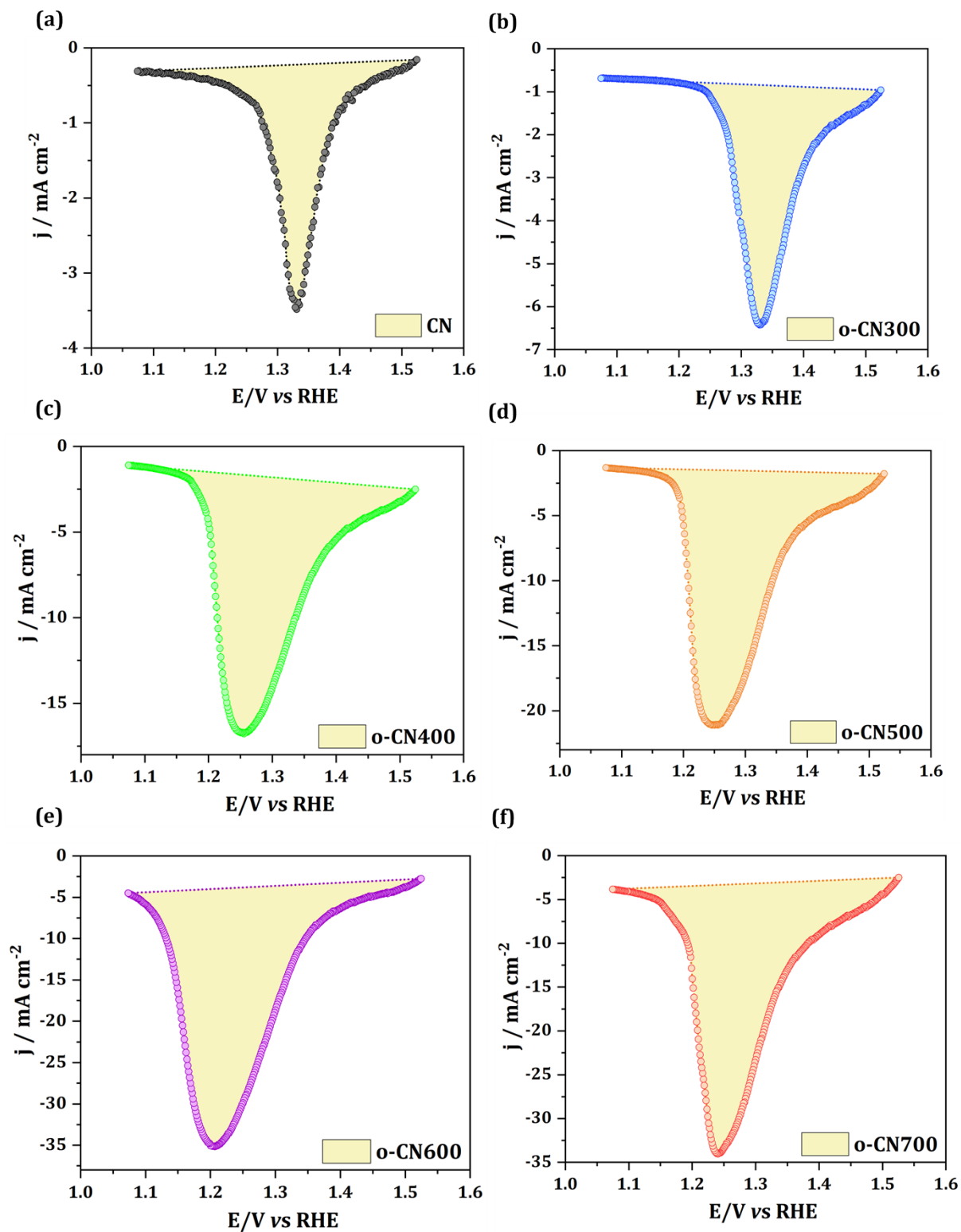


Figure S9: Backward CV scans collected for CN and o-CNX in 1.0 M KOH, serving as the basis for evaluating the ECAS (a–f).

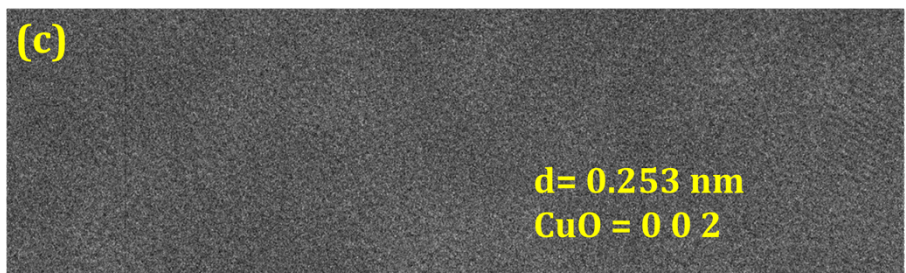
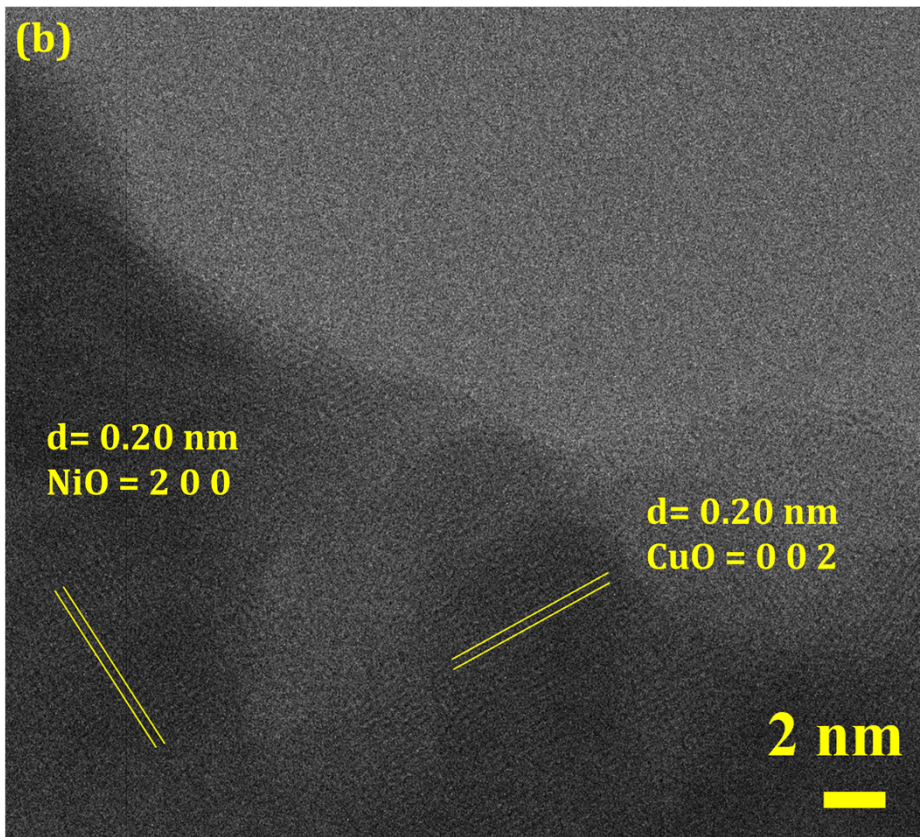
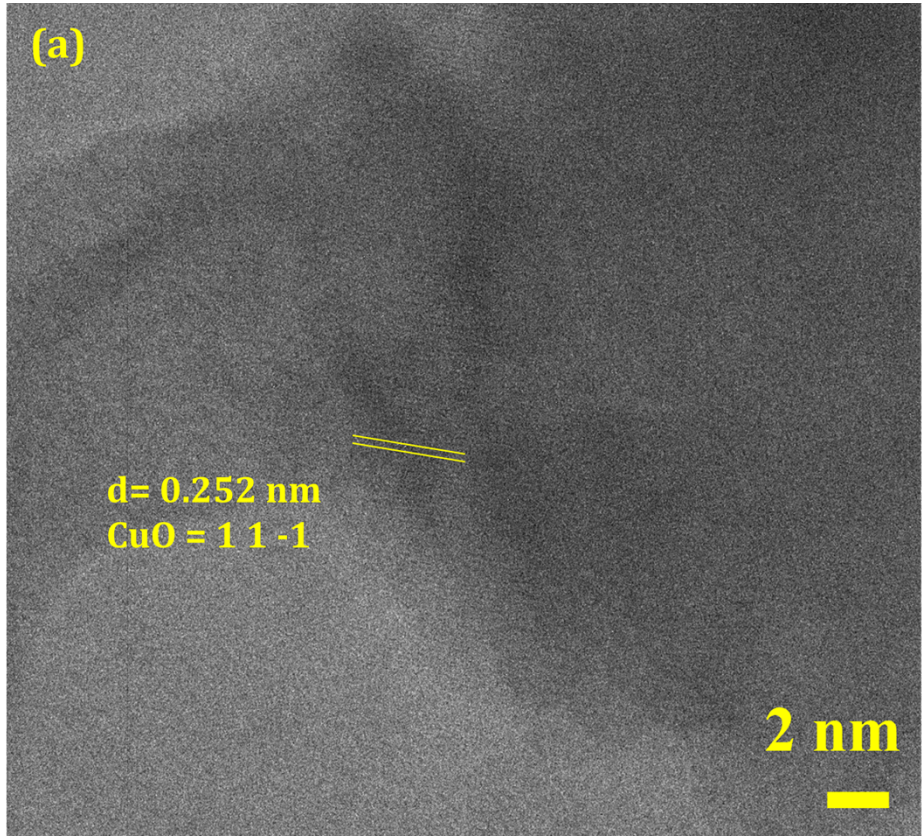


Figure S10. High-resolution HRTEM images of the o-CN500, o-CN600, and o-CN700 samples shown in Figure 3. Panels are labeled in this figure as (a) - (c), corresponding to the main manuscript labels k, o, and s, respectively.

XPS Analysis and Mechanistic Insight:

Table S1. XPS-derived Ni²⁺/Ni³⁺ ratios of the o-CN600 catalyst before and after the stability test

o-CN600	Ni²⁺/Ni³⁺	%Ni²⁺	%Ni³⁺
Before Stability	1.13	53.08	46.92
After Stability	1.83	64.59	35.41

Table S2. Comparison of the OER electrocatalytic performance of recently reported Cu–Ni-based catalysts and the present o-CN600 catalyst in alkaline electrolyte. The overpotential (η) values are compared at their corresponding current densities.

S. No.	Catalyst	OER Overpotential (η)	Current Density (mA cm⁻²)
1	CuNiPx-GDY (1:1) ¹	178 mV	10 mA cm ⁻²
2	CuNiPd (CNP-3) ²	256 mV	10 mA cm ⁻²
3	(Co _{0.21} Ni _{0.25} Cu _{0.54}) ₃ Se ₂ ³	272 mV	10 mA cm ⁻²
4	CuNi/CoFe LDH@NF ⁴	268 mV	50 mA cm ⁻²
5	CuNi@NiFeCu ⁵	285 mV	50 mA cm ⁻²
6	Cu ₅₀ Ni ₅₀ NP ⁶	318 mV	10 mA cm ⁻²
7	CuNi@Ni(ON)/CNTs-Gr ⁷	410 mV	100 mA cm ⁻²
8	o-CN600 (Present work)	372 mV	10 mA cm⁻²

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